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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6V
Data Converters	
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c622-20-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



EPROM-Based 8-Bit CMOS Microcontrollers

Devices included in this data sheet:

Referred to collectively as PIC16C62X.

- PIC16C620 PIC16C620A
- PIC16C621 PIC16C621A
- PIC16C622 PIC16C622A
- PIC16CR620A

High Performance RISC CPU:

- Only 35 instructions to learn
- All single cycle instructions (200 ns), except for program branches which are two-cycle
- Operating speed:
 - DC 40 MHz clock input
 - DC 100 ns instruction cycle

Device	Program Memory	Data Memory
PIC16C620	512	80
PIC16C620A	512	96
PIC16CR620A	512	96
PIC16C621	1K	80
PIC16C621A	1K	96
PIC16C622	2K	128
PIC16C622A	2K	128

· Interrupt capability

- 16 special function hardware registers
- 8-level deep hardware stack
- Direct, Indirect and Relative addressing modes

Peripheral Features:

- 13 I/O pins with individual direction control
- High current sink/source for direct LED drive
- Analog comparator module with:
- Two analog comparators
- Programmable on-chip voltage reference (VREF) module
- Programmable input multiplexing from device inputs and internal voltage reference
- Comparator outputs can be output signals
- Timer0: 8-bit timer/counter with 8-bit programmable prescaler

Pin Diagrams

PDIP, SOIC, Windowed CERDIP



Special Microcontroller Features:

- · Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Reset
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- · Programmable code protection
- · Power saving SLEEP mode
- Selectable oscillator options
- Serial in-circuit programming (via two pins)
- Four user programmable ID locations

CMOS Technology:

- Low power, high speed CMOS EPROM technology
- Fully static design
- · Wide operating range
 - 2.5V to 5.5V
- Commercial, industrial and extended temperature range
- Low power consumption
 - < 2.0 mA @ 5.0V, 4.0 MHz
 - 15 μA typical @ 3.0V, 32 kHz
 - < 1.0 μA typical standby current @ 3.0V

Device Differences

Device	Voltage Range	Oscillator	Process Technology (Microns)
PIC16C620 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C621 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C622 ⁽³⁾	2.5 - 6.0	See Note 1	0.9
PIC16C620A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7
PIC16CR620A ⁽²⁾	2.5 - 5.5	See Note 1	0.7
PIC16C621A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7
PIC16C622A ⁽⁴⁾	2.7 - 5.5	See Note 1	0.7

Note 1: If you change from this device to another device, please verify oscillator characteristics in your application.

2: For ROM parts, operation from 2.5V - 3.0V will require the PIC16LCR62X parts.

3: For OTP parts, operation from 2.5V - 3.0V will require the PIC16LC62X parts.

4: For OTP parts, operations from 2.7V - 3.0V will require the PIC16LC62XA parts.

4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C62X has a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C620(A) and PIC16CR620, 1K x 14 (0000h - 03FFh) for the PIC16C621(A) and 2K x 14 (0000h - 07FFh) for the PIC16C622(A) are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 space (PIC16C(R)620(A)) or 1K x 14 space (PIC16C621(A)) or 2K x 14 space (PIC16C622(A)). The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2, Figure 4-3).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C620/PIC16C620A/

PIC16CR620A



FIGURE 4-2:

PROGRAM MEMORY MAP AND STACK FOR THE PIC16C621/PIC16C621A



FIGURE 4-3:

PROGRAM MEMORY MAP AND STACK FOR THE PIC16C622/PIC16C622A



4.2 Data Memory Organization

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

OPTION Register 4.2.2.2

The OPTION register is a readable and writable register, which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note:	To achieve a 1:1 prescaler assignment for
	TMR0, assign the prescaler to the WDT
	(PSA = 1).

REGISTER 4-2:	OPTION REGISTER (ADDRESS 81H)
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RBPU INTEDG TOCS TOSE bit 7 bit 7 RBPU: PORTB Pull-up Enable bit 1 = PORTB pull-ups are disabled 0 = PORTB pull-ups are enabled by individual por bit 6 INTEDG: Interrupt Edge Select bit 1 = Interrupt on rising edge of RB0/INT pin 0 = Interrupt on falling edge of RB0/INT pin 0 = Interrupt on falling edge of RB0/INT pin bit 5 TOCS: TMR0 Clock Source Select bit 1 = Transition on RA4/T0CKI pin 0 = Internal instruction cycle clock (CLKOUT) bit 4 TOSE: TMR0 Source Edge Select bit 1 = Increment on high-to-low transition on RA4/T0 0 = Increment on low-to-high transition on RA4/T0 bit 3 PSA: Prescaler Assignment bit	PSA t latch va DCKI pin DCKI pin	PS2	PS1	PS0 bit 0						
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0 = Increment on low-to-high transition on RA4/T0 bit 3 PSA : Prescaler Assignment bit	OCKI pin									
bit 3 PSA : Prescaler Assignment bit										
1 = Prescaler is assigned to the WDT	1 = Prescaler is assigned to the WDT									
0 = Prescaler is assigned to the Timer0 module										
bit 2-0 PS<2:0> : Prescaler Rate Select bits										
Bit Value TMR0 Rate WDT Rate										
000 1:2 1:1										
001 1:4 1:2										
101 1:64 1:32										
110 1:128 1:64										
111 1:256 1:128										

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for all interrupt sources except the comparator module. See Section 4.2.2.4 and Section 4.2.2.5 for a description of the comparator enable and flag bits.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>).

	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x			
	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF			
	bit 7			<u>.</u>		<u>.</u>		bit 0			
bit 7	GIE: Globa	I Interrupt E	nable bit								
	1 = Enables	s all un-mas	sked interrup	ots							
1.11.0		s all interru	pts								
0 110	PEIE: Perip		upt Enable i	DIT 	-						
	1 = Enables 0 = Disable	s all un-mas	sked periphe eral interrun	eral interrupt	S						
bit 5		0 Overflow	Interrunt En	able bit							
bit o	1 = Enables	s the TMR0	interrupt								
	0 = Disable	s the TMR) interrupt								
bit 4	INTE: RB0/	INTE: RB0/INT External Interrupt Enable bit									
	1 = Enables	s the RB0/I	NT external	interrupt							
	0 = Disable	s the RB0/I	NT external	interrupt							
bit 3	RBIE: RB F	ort Change	Interrupt E	nable bit							
	1 = Enables	s the RB po	rt change in	iterrupt							
L:4 0			oft change in	iterrupi							
DIL ∠		J OVernow i		g Dit	- ared in coff	+					
	1 = TMR0 r 0 = TMR0 r	register did	not overflow	(ที่มีประ มีฮ มีฮ /	aleu ili son	ware					
bit 1	INTF: RB0/	INT Externa	al Interrupt F	-lag bit							
	1 = The RB	30/INT exter	nal interrup	t occurred (n	nust be clea	ared in softw	are)				
	0 = The RB	30/INT exter	nal interrupt	t did not occ	ur						
bit 0	RBIF : RB F	ort Change	Interrupt Fl	lag bit							
	1 = When a	at least one	of the RB<7	':4> pins cha	anged state	(must be cle	ared in soft	ware)			
	0 = None o	f the RB<1	4> pins nave	e changea s	tate						
	Larandi										
	Legend:										

REGISTER 4-3:	INTCON REGISTER (ADDRESS 0BH OR 8BH)	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any RESET, the PC is cleared. Figure 4-8 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> \rightarrow PCH). The lower example in the figure shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> \rightarrow PCH).

FIGURE 4-8: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note, *"Implementing a Table Read"* (AN556).

4.3.2 STACK

The PIC16C62X family has an 8-level deep x 13-bit wide hardware stack (Figure 4-2 and Figure 4-3). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

- Note 1: There are no STATUS bits to indicate stack overflow or stack underflow conditions.
 - 2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

TABLE 5-1:PORTA FUNCTIONS

Name	Bit #	Buffer Type	Function			
RA0/AN0	bit0	ST	Input/output or comparator input			
RA1/AN1	bit1	ST	Input/output or comparator input			
RA2/AN2/VREF	bit2	ST	Input/output or comparator input or VREF output			
RA3/AN3	bit3	ST	Input/output or comparator input/output			
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0 or comparator output. Output is open drain type.			

Legend: ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
05h	PORTA		_		RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
85h	TRISA	_	_	_	TRISA 4	TRISA 3	TRISA 2	TRISA 1	TRISA 0	1 1111	1 1111
1Fh	CMCON	C2OUT	C1OUT	_	_	CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown

Note: Shaded bits are not used by PORTA.









7.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 7-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator

mode is changed, the comparator output level may not be valid for the specified mode change delay shown in Table 12-2.

Note: Comparator interrupts should be disabled during a Comparator mode change otherwise a false interrupt may occur.







FIGURE 9-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2



FIGURE 9-10: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)



RETFIE	Return from Interrupt								
Syntax:	[label] RETFIE								
Operands:	None								
Operation:	$\begin{array}{l} TOS \to PC, \\ 1 \to GIE \end{array}$								
Status Affected:	None								
Encoding:	00 0000 0000 1003								
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction.								
Words:	1								
Cycles:	2								
Example	RETFIE								
	After Inte	rrupt PC = GIE =	TOS 1						

RETLW	Return with Literal in W								
Syntax:	[<i>label</i>] RETLW k								
Operands:	$0 \le k \le 255$								
Operation:	$k \rightarrow (W);$ TOS \rightarrow PC								
Status Affected:	None								
Encoding:	11 01xx kkkk kkkk								
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.								
Words:	1								
Cycles:	2								
Example	CALL TABLE;W contains table								
TABLE	;offset value ;W now has table value • ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ;								
	• RETLW kn ; End of table Before Instruction W = 0x07 After Instruction W = value of k8								
RETURN	Return from Subroutine								
Syntax:	[label] RETURN								
Operands:	None								
Operation:	$TOS \rightarrow PC$								
Status Affected:	None								
Encoding:	00 0000 0000 1000								
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.								
Words:	1								
Cycles:	2								
Example	RETURN								
	After Interrupt PC = TOS								

11.9 MPLAB ICE 2000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 2000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PICmicro microcontrollers. Software control of the MPLAB ICE 2000 in-circuit emulator is advanced by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PICmicro microcontrollers.

The MPLAB ICE 2000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft[®] Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

11.10 MPLAB ICE 4000 High Performance Universal In-Circuit Emulator

The MPLAB ICE 4000 universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for highend PICmicro microcontrollers. Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment, which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICD 4000 is a premium emulator system, providing the features of MPLAB ICE 2000, but with increased emulation memory and high speed performance for dsPIC30F and PIC18XXXX devices. Its advanced emulator features include complex triggering and timing, up to 2 Mb of emulation memory, and the ability to view variables in real-time.

The MPLAB ICE 4000 in-circuit emulator system has been designed as a real-time emulation system with advanced features that are typically found on more expensive development tools. The PC platform and Microsoft Windows 32-bit operating system were chosen to best make these features available in a simple, unified application.

11.11 MPLAB ICD 2 In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD 2, is a powerful, low cost, run-time development tool, connecting to the host PC via an RS-232 or high speed USB interface. This tool is based on the FLASH PICmicro MCUs and can be used to develop for these and other PICmicro microcontrollers. The MPLAB ICD 2 utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming[™] (ICSP[™]) protocol, offers cost effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by setting breakpoints, single-stepping and watching variables, CPU status and peripheral registers. Running at full speed enables testing hardware and applications in real-time. MPLAB ICD 2 also serves as a development programmer for selected PICmicro devices.

11.12 PRO MATE II Universal Device Programmer

The PRO MATE II is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features an LCD display for instructions and error messages and a modular detachable socket assembly to support various package types. In Stand-Alone mode, the PRO MATE II device programmer can read, verify, and program PICmicro devices without a PC connection. It can also set code protection in this mode.

11.13 PICSTART Plus Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus development programmer supports most PICmicro devices up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.









12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62XA				$\begin{tabular}{ c c c c c } \hline Standard Operating Conditions (unless otherwise stated) \\ Operating temperature & -40°C & \leq TA \leq +85°C \mbox{ for industrial and} \\ & 0°C & \leq TA \leq +70°C \mbox{ for commercial and} \\ & -40°C & \leq TA \leq +125°C \mbox{ for extended} \end{tabular}$						
PIC16LC62XA			$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Param. No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions			
D010	IDD	Supply Current ^(2, 4)	_	1.2 0.4	2.0 1.2	mA mA	Fosc = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)* Fosc = 4 MHz, VDD = 3.0V, WDT disabled, XT mode (Note 4)*			
				1.0 4.0	2.0 6.0	mA mA	Fosc = 10 MHz, VDD = 3.0V, WDT dis- abled, HS mode, (Note 6) Fosc = 20 MHz, VDD = 4.5V, WDT dis-			
			-	4.0 35	7.0 70	mA μA	abled, HS mode Fosc = 20 MHz, VDD = 5.5V, WDT dis- abled*, HS mode Fosc = 32 kHz, VDD = 3.0V, WDT dis- abled, LP mode			
D010	IDD	Supply Current ⁽²⁾	_	1.2	2.0 1.1	mA mA	Fosc = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)* Fosc = 4 MHz, VDD = 2.5V, WDT disabled, XT mode, (Note 4)			
			_	35	70	μA	Fosc = 32 kHz, VDD = 2.5V, WDT dis- abled, LP mode			
D020	IPD	Power-down Current ⁽³⁾	 		2.2 5.0 9.0 15	μΑ μΑ μΑ μΑ	VDD = 3.0V VDD = 4.5V* VDD = 5.5V VDD = 5.5V VDD = 5.5V Extended Temp.			
D020	IPD	Power-down Current ⁽³⁾	 	 	2.0 2.2 9.0 15	μΑ μΑ μΑ μΑ	VDD = 2.5V VDD = 3.0V* VDD = 5.5V VDD = 5.5V Extended Temp.			

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.3 DC CHARACTERISTICS: PIC16CR62XA-04 (Commercial, Industrial, Extended) PIC16CR62XA-20 (Commercial, Industrial, Extended) PIC16LCR62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16CR62XA-04		Standard Operating Conditions (unless otherwise stated)							
		Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial and							
PIC16CR62XA-20			$0^{\circ}C < TA < +70^{\circ}C$ for commercial a						
			$-40^{\circ}C \leq TA \leq +125^{\circ}C$ for extended						
			Standard Operating Conditions (unless otherwise stated)						
		Operating temperature -40° C $<$ Ta $< +85^{\circ}$ C for industrial and							
PIC16LCR62XA-04		opora	ling ton	porat		0° C < TA < +70°C for commercial and			
						-40	1° C < TA < +125°C for extended		
Dorom	Sum	Characteristic	Min	Tunt	Mox	Unito			
No	Sym	Characteristic	IVIIII	турт	wax	Units	conditions		
NU.	1	(2)			050				
D020	IPD	Power-down Current ⁽³⁾		200	950	nA	VDD = 3.0V		
				0.400	1.0	μΑ			
				0.600	2.2	μΑ	VDD - 5.5V		
Daga	1	- (0)	_	5.0	9.0	μΑ	VDD – 5.5V Extended Temp.		
D020	IPD	Power-down Current ⁽³⁾		200	850	nA	VDD = 2.5V		
				200	950	nA A	$VDD = 3.0V^{\circ}$		
			_	0.600	2.2	μΑ	VDD = 5.5V		
D aga		(5)		5.0	9.0	μΑ			
D022	Δ IWDT	WD1 Current ⁽³⁾		6.0	10	μA	VDD=4.0V		
D0004	415.05	Decours out Decot Quere at(5)		75	12	μΑ	$\frac{(125^{\circ}C)}{DOD}$		
DUZZA		Brown-out Reset Current(*)		75	125	μΑ	BOD enabled, VDD = $5.0V$		
D023		Comparator Current for each		30	60	μΑ	VDD - 4.0V		
00234		Vere Current ⁽⁵⁾		80	125		$V_{DD} = 4.0V$		
DOZJA		WDT Current ⁽⁵⁾		00	100	μΑ	VDD = 4.0V		
D022		wDT Current(**		6.0	10	μΑ	VDD-4.0V (125°C)		
00224		Brown out Posot Current ⁽⁵⁾		75	12	μΑ	$\frac{(125)}{125}$ C)		
D022A		Comparator Current for each		30	60	μΑ	BOD ellabled, VDD = 5.0°		
0025		Comparator ⁽⁵⁾		50	00	μΛ	VDD - 4.0V		
D023A	Δ IVREF	VREF Current ⁽⁵⁾		80	135	μA	VDD = 4.0V		
1A	Fosc	LP Oscillator Operating Frequency	0	_	200	kHz	All temperatures		
		RC Oscillator Operating Frequency	0		4	MHz	All temperatures		
		XT Oscillator Operating Frequency	0		4	MHz	All temperatures		
		HS Oscillator Operating Frequency	0		20	MHz	All temperatures		
1A	Fosc	LP Oscillator Operating Frequency	0		200	kHz	All temperatures		
		RC Oscillator Operating Frequency	0		4	MHz	All temperatures		
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures		
HS Oscillator Operating Frequency			0	—	20	MHz	All temperatures		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

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3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.









14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



	Units	INCHES*			MILLIMETERS		
Dimension	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		18			18	
Pitch	р		.100			2.54	
Top to Seating Plane		.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height		.155	.160	.165	3.94	4.06	4.19
Standoff		.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	В	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
 § Significant Characteristic
 JEDEC Equivalent: MO-036
 Drawing No. C04-010

APPENDIX A: ENHANCEMENTS

The following are the list of enhancements over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14 bits. This allows larger page sizes both in program memory (4K now as opposed to 512 before) and register file (up to 128 bytes now versus 32 bytes before).
- 2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
- 3. Data memory paging is slightly redefined. STATUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.
 Two instructions TRIS and OPTION are being phased out, although they are kept for compatibility with PIC16C5X.
- 5. OPTION and TRIS registers are made addressable.
- 6. Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. RESET vector is changed to 0000h.
- RESET of all registers is revisited. Five different RESET (and wake-up) types are recognized. Registers are reset differently.
- 10. Wake-up from SLEEP through interrupt is added.
- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt-onchange feature.
- 13. Timer0 clock input, T0CKI pin is also a port pin (RA4/T0CKI) and has a TRIS bit.
- 14. FSR is made a full 8-bit register.
- 15. "In-circuit programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, VPP, RB6 (clock) and RB7 (data in/out).
- PCON STATUS register is added with a Poweron-Reset (POR) STATUS bit and a Brown-out Reset STATUS bit (BOD).
- 17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- 18. PORTA inputs are now Schmitt Trigger inputs.
- 19. Brown-out Reset reset has been added.
- 20. Common RAM registers F0h-FFh implemented in bank1.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- 1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change RESET vector to 0000h.

NOTES: